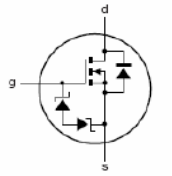
V_{DSS}	60	V
I_D	340	mA
$R_{DS(ON)}$	1.7	Ω

FEATURE

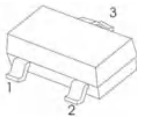
- High density cell design for low $R_{DS(ON)}$
- Voltage controlled small signal switch
- Rugged and reliable
- High saturation current capability

7002

Equivalent Circuit



SOT-23



1. GATE
2. SOURCE
3. DRAIN

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings

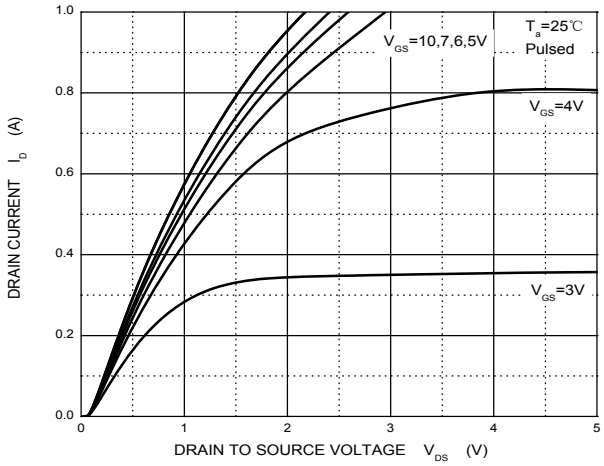
Symbol	Parameter	Value	Units
V_{DS}	Drain-Source voltage	60	V
V_{GS}	Gate-Source voltage	20	V
I_D	Drain Current	340	mA
P_D	Power Dissipation	0.35	W
T_J	Junction Temperature	150	℃
T_{stg}	Storage Temperature	-55-150	℃
$R_{\theta JA}$	Thermal Resistance fromJunction to Ambient	357	℃ /W

Electrical Characteristics T_J=25℃ unless otherwise s ecified

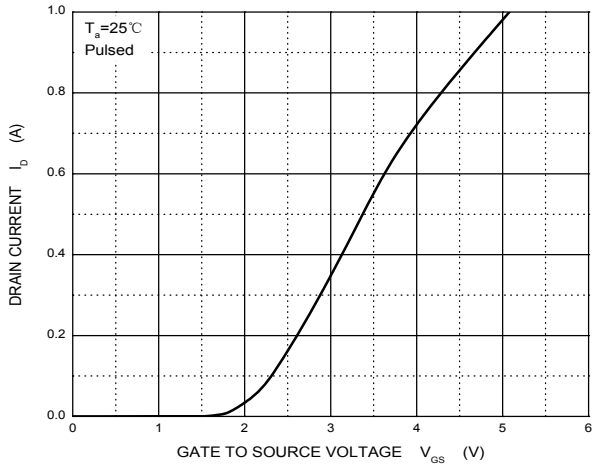
Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Static Characteristics						
Drain-Source Breakdown Voltage	V_{DS}	V_{GS} = 0V, I_D =250μA	60			V
Gate Threshold Voltage*	$V_{GS(th)}$	V_{DS} =V_{GS}, I_D =1mA	1		2.5	V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} =48V,V_{GS} = 0V			1	μA
Gate –Source leakage current	I_{GSS1}	V_{GS} =±20V, V_{DS} = 0V			±10	μA
	I_{GSS2}	V_{GS} =±10V, V_{DS} = 0V			±200	nA
	I_{GSS3}	V_{GS} =±5V, V_{DS} = 0V			±100	nA
Drain-Source On-Resistance*	$R_{DS(on)}$	V_{GS} = 4.5V, I_D =200mA			5.3	Ω
		V_{GS} =10V,I_D =500mA		1.7	5	Ω
Diode Forward Voltage	V_{SD}	V_{GS}=0V, I_S=300mA			1.5	V
Recovered charge	Q_r	V_{GS}=0V,I_S=300mA,V_R=25V, dI_S/dt=-100A/μS		30		nC
Dynamic Characteristics**						
Input Capacitance	C_{iss}	V_{DS} =10V,V_{GS} =0V,f =1MHz			40	pF
Output Capacitance	C_{oss}				30	pF
Reverse Transfer Capacitance	C_{rss}				10	pF
Switching Characteristics**						
Turn-On Delay Time	$t_{d(on)}$	V_{GS}=10V,V_{DD}=50V,R_G=50Ω, R_{GS}=50Ω, R_L=250Ω			10	ns
Turn-Off Delay Time	$t_{d(off)}$				15	ns
Reverse recovery Time	t_{rr}	V_{GS}=0V,I_S=300mA,V_R=25V, dI_S/dt=-100A/μS		30		ns
GATE-SOURCE ZENER DIODE						
Gate-Source Breakdown Voltage	BV_{GSO}	I_{gs}=±1mA (Open Drain)	±21.5		±30	V

RATING AND CHARACTERISTIC CURVES

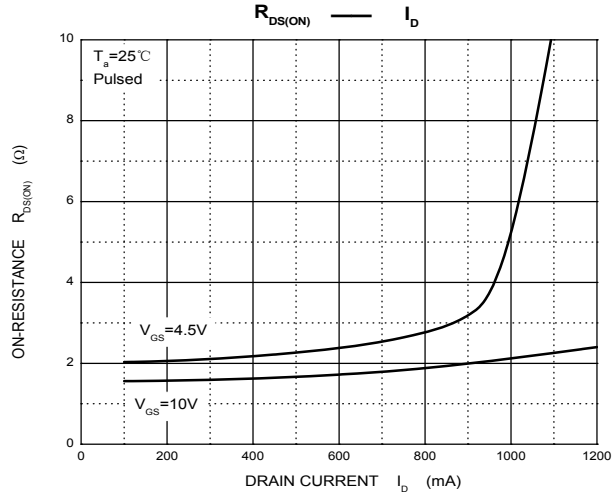
Output Characteristics



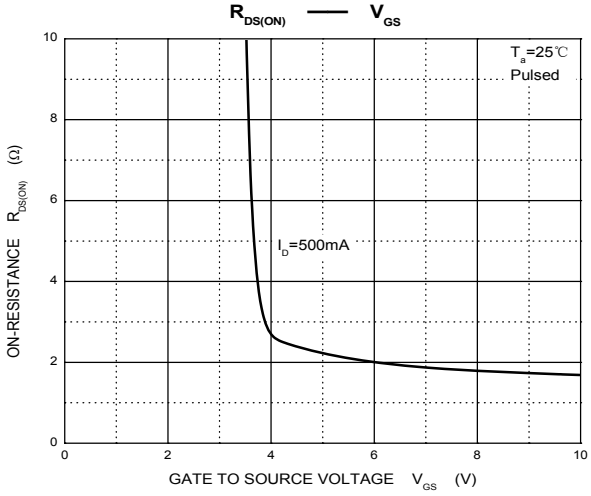
Transfer Characteristics



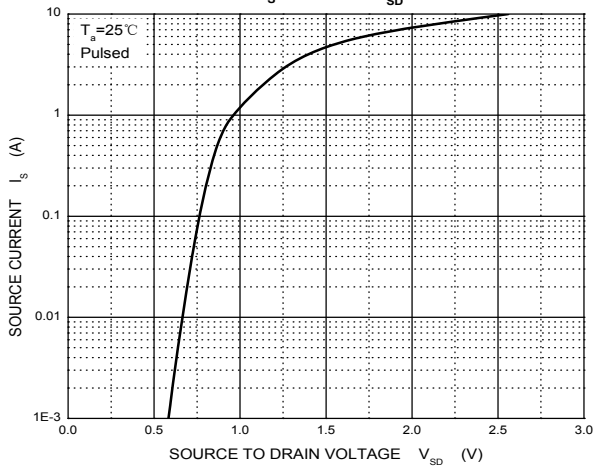
$R_{DS(ON)}$ — I_D



$R_{DS(ON)}$ — V_{GS}



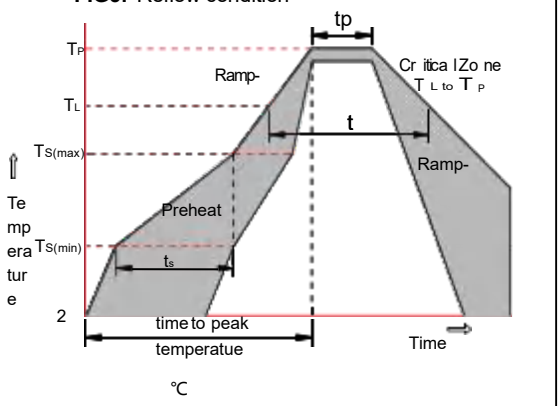
I_S — V_{SD}



Soldering parameters

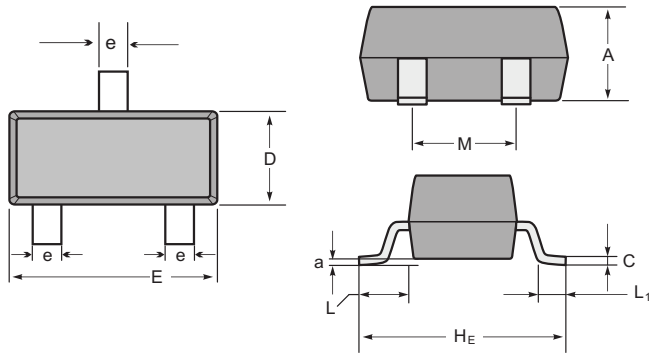
Reflow Condition		Pb-Free assembly (see as bellow)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150℃
	-Temperature Max($T_{s(max)}$)	+200℃
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3℃/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3℃/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217℃
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)℃
Time within 5℃ of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6℃/sec. Max
Time 25℃ to Peak Temp (T_P)		8 min. Max
Do not exceed		+260℃

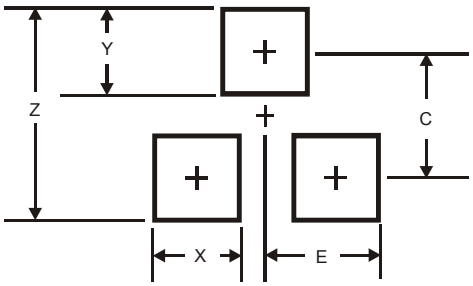
FIG5: Reflow condition



Package Dimensions & Suggested Pad Layout

SOT23





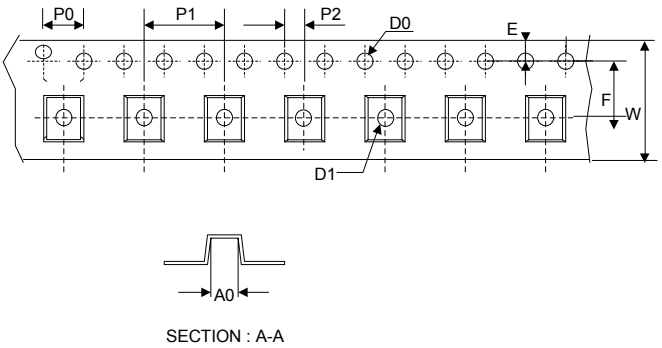
SOT-23 mechanical data

UNIT		A	C	D	E	H_E	e	M	L	L_1	a
mm	max	1.1	0.15	1.4	3.0	2.6	0.5	1.95	0.55 (ref)	0.36 (ref)	0.0
	min	0.9	0.08	1.2	2.8	2.2	0.3	1.7			0.15
mil	max	43	6	55	118	102	20	77	22 (ref)	14 (ref)	0.0
	min	35	3	47	110	87	12	67			6

Dimensions	SOT23
Z	2.9
X	0.8
Y	0.9
C	2.0
E	1.35

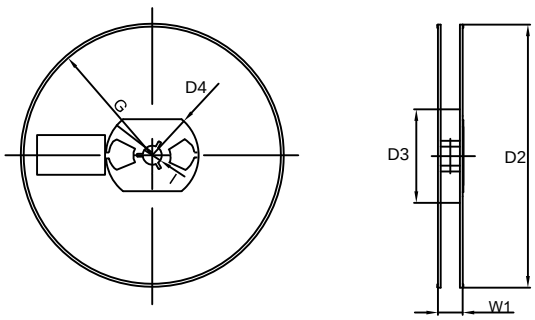
Tape & rell specification

Tape



Symbol	Dimension (mm)
P0	4.00±0.10
P1	4.00±0.10
P2	2.00±0.10
D0	1.55±0.10
D1	1.05±0.10
E	1.55±0.10
F	3.60±0.10
W	8.00±0.10
A0	3.80±0.20
B0	3.25±0.20
K0	1.45±0.10
T	0.25±0.05

7” Reel



D2	178.0±3.0
D3	55Min.
D4	R24.0±3.0
G	R82.0±3.0
I	13.0±2.0
W1	11.0±3.0

Quantity: 3000PCS